

Neosid Pemetzrieder GmbH & Co. KG will realise the guideline 2002/95/EG/ RoHS, especially the requirement of lead free soldering, already before the deadline of 01. July 2006.

Beginning with 1. Mai 2005 we will change our components production to lead free. The solder alloy will be Sn-Ag-Cu. It has been proven by our investigations that the components can be used under the temperature profiles according to IEC 61760-1 ED2 and IEC 60068-2-58.

Regarding SM-Components with plastic parts we recommend to verify the temperature profile of your process with the results of the Neosid tests. You can order samples from us.

Stock of SnPb components will be delivered according to the FiFo rule.
The packing of lead free components will be labelled with a corresponding sticker.

Please feel free to contact us for any further questions.